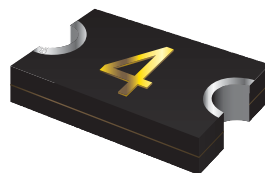


MATERIAL DECLARATION SHEET



Material	MF-NSMFxxxX
Product Line	Multifuse
Revision Date	Apr. 01, 2009
Revision	B
RoHS Compliant	Yes
Halogen Free Compliant	Yes



No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams ($\pm 0.1\%$)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Carbon Black	Carbon	0.0002366	1333-86-4	2.64%	2.64%
2	Copper plating	Copper	0.0032802	7440-50-8	36.64%	36.64%
3	Foil	Copper	0.0029088	7440-50-8	32.49%	34.20%
		Nickel	0.0001531	7440-02-0	1.71%	
4	PCB Foil	Copper	0.0008505	7440-50-8	9.50%	9.50%
5	Polymer	Polyethylene Homopolymer	0.0002096	9002-88-4	2.34%	2.34%
		Proprietary Additives ¹	0.0000003	-	0.00%	
6	Prepreg	Epoxy	0.0007667	35948-25-5	8.56%	14.27%
		Glass fiber	0.0005111	65997-17-3	5.71%	
7	Soldering plating	Nickel	0.0000350	7440-02-0	0.39%	0.40%
		Gold	0.0000005	7440-57-5	0.01%	
		Total Weight (%)				

Total weight (grams)	0.0089525	Total	100%	100%
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¹ Proprietary Additives materials contain no banned substances